

Very Low Loss and High Thermal Reliability Laminate and Prepreg





Delivering Value through Innovation and Dedication

ThunderClad 3E / TU-933E

Prepreg: TU-933P E

Core: TU-933E

ThunderClad 3E / TU-933E is an advanced material designed for high speed computing, telecommunications, radio frequency super low loss filed applications. TU-933E's electrical performance is competitive with hydrocarbon-based very low loss materials, but capable for high layer count circuit board design with excellent thermal reliability.

TU-933E laminates also exhibit excellent moisture resistance, improved CTE, superior chemical resistance, thermal stability, CAF resistance, and also compatible with modified FR-4 processes.

Applications

- Radio frequency
- Backpanel, High performance computing

Lead Free

- Line cards, Storage
- Servers, Telecom, Base station
- Office Routers

Performance and Processing Advantages

- Excellent electrical and thermal properties
- Dielectric constant is 3.5 @ 10Gz
- Dissipation factor is 0.0036 @ 10Ghz
- Stable and flat Dk/Df performance over frequency and temperature variance.
- Compatible with modified FR-4 processes
- Excellent moisture resistance and Lead Free reflow process compatible
- Improved z-axis thermal expansion
- Superior dimensional stability, thickness uniformity and flatness
- Anti-CAF capability
- Excellent through-hole and soldering reliability

Industry Approvals

- IPC-4101E Specification Number : /102
- IPC-4101E/102 Validation Services QPL Certified
- UL File Number: E189572
- ANSI Grade: no-ANSI
- Flammability Rating: 94V-0
- Maximum Operating Temperature: 140°C

Standard Availability

- Thickness: 0.002" [0.05mm] to 0.062" [1.58mm], available in sheet or panel form
- Copper Foil Cladding: 1/3 to 3 oz for built-up & double sides
- Prepregs: Available in roll or panel form
- Glass Styles: 1078, 1086, and other prepreg grades are available upon request.





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tucc台燿科技 Taiwan Union Technology Corporation (TUC) www.tuc.com.tw

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	Typical Values	Conditioning
Thermal		
Tg (DMA)	220 ℃	
Tg (TMA)	170 °C	E-2/105
Td (TGA)	390 ℃	
CTE α1	35 ppm/°C	
CTE α2	250 ppm/°C	E-2/105
CTE z-axis	2.7 %	
Thermal Stress,		
Solder Float, 288°C	> 120 sec	A
T-260	> 60 min	
T-288	> 60 min	E-2/105
T-300	> 60 min	
Flammability	94V-0	E-24/125
Electrical		
Permittivity (RC65%)		
10 GHz (SPC method)	3.50	E-2/105
Loss Tangent (RC65%)		
10 GHz (SPC method)	0.0036	E-2/105
Volume Resistivity	> 10 ¹⁰ MΩ · cm	C-96/35/90
Surface Resistivity	$> 10^8 \text{ M}\Omega$	C-96/35/90
Electric Strength	> 40 KV/mm	А
Dielectric Breakdown Voltage	> 50 KV	А
Mechanical		
Young's Modulus		
Warp Direction	23 GPa	А
Fill Direction	21 GPa	Α
Flexural Strength		
Lengthwise	> 60,000 psi	А
Crosswise	> 50,000 psi	
Peel Strength,		
1.0 oz. Cu foil	4~7 lb/in	А
Water Absorption	0.06 %	E-1/105 + D-24/23

NOTE:

1. Property values are for information purposes only and not intended for specification.

2. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold.

3. This product is based on a patent pending technology.

